

Title (en)

A PROCESS AND APPARATUS FOR IMPROVING AND CONTROLLING THE CURING OF NATURAL AND SYNTHETIC MOLDABLE COMPOUNDS

Title (de)

PROZESS UND VORRICHTUNG ZUM VERBESSERN UND STEUERN DER AUSHÄRTUNG VON NATÜRLICHEN UND SYNTHETISCHEN FORMBAREN ZUSAMMENSETZUNGEN

Title (fr)

PROCEDE ET APPAREIL POUR AMELIORER ET CONTROLER LA VULCANISATION DE COMPOSES MOULABLES SYNTHETIQUES ET NATURELS

Publication

**EP 1741010 A2 20070110 (EN)**

Application

**EP 05725438 A 20050311**

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Abstract (en)

[origin: WO2005086965A2] A process for curing a moldable compound under a plurality of curing conditions by: (1) obtaining time dependent data streams of dielectric or impedance values from a plurality of sensors distributed within a curing mold, wherein the moldable compound is a dielectric for each of the sensors; (2) determining impedance related measurements from the data streams for the plurality of sensors; (3) determining predictive and/or corrective curing actions for enhancing the curing process using the impedance related measurements for the plurality of sensors; and (4) controlling the mass production curing of parts to obtain cured parts having one or more desired properties.

IPC 8 full level

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